Preliminary Program Overview, rev1.4 *(Subject to updates and changes)*

	DAY 1: December 2, 2025
07:30am - 08:45am	Registration
Venue	West Ballroom
08:45am - 09:00am	Opening Ceremony & Welcome Speech
09:00am - 09:45am	Keynote 1: Dr Akshay Singh, VP, Micron Technology
09:45am - 10:30am	Keynote 2: Audrey Charles, SVP, Lam Research
10:30am - 11:00am	30min Coffee Break @ West Ballroom Foyer
11:00am - 12:30pm	Panel Session 1: *TBC*
12:30pm - 12:50pm	Advanced Packaging Solutions Presentation: by Lam Research (Diamond Sponsor)
Venue	West Ballroom Foyer
12:50pm - 1:50pm	Lunch @ West Ballroom Foyer
Venue	West Ballroom
1:50pm - 2:35pm	Keynote 3: Dr Radha Nagaranjan, SVP and CTO, Marvell
2:35pm - 3:20pm	Keynote 4: Pax Wang, TD Director, UMC
3:20pm - 3:50pm	30min Coffee Break @ West Ballroom Foyer
3:50pm - 4:05pm	Products Presentation: by Applied Materials (Platinum Sponsor)
4:05pm - 4:20pm	Products Presentation: by KLA Tenco (Platinum Sponsor)
4:20pm - 5:50pm	Panel Session 2: Metrology and Test Readiness for Heterogeneous Integration
5:50pm - 6:15pm	Welcome Reception @ outside West Ballroom

DAY 2: December 3, 2025

Venue	Aquarius 1	Aquarius 2	Aquarius 3	Aquarius 4	Gemini 1	Gemini 2
08:30am - 10:00am	**PDC1**	**PDC2**	**PDC3**	**PDC4**	**PDC5**	**PDC6**
	Advanced Packaging for Chiplets, Heterogenous Integration and CPO Dr John Lau (Unimicron)	Photonic Components and Packaging Technologies for Data Center, Communications, Sensing and Displays Dr Torsten Wipiejewski (Huawei)	Advanced Packaging for MEMS and Sensors Dr Horst Theuss (Infineon)	Current and Future Challenges and Solutions in AI & HPC System and Thermal Management Dr Gamal Refai-Ahmed (AMD)	Overview of Characterization Techniques for 3D HI Circuit Packaging Prof Ali Shakouri (Purdue University)	Design-on Simulation Technology for Reliability Prediction of AP Prof K.N. Chiang (National Tsing Hua University)
10:00am - 10:30am	30min Coffee Break outside Exhibition Hall (Leo 1-4)					
10:30am - 12:00pm	PDC1 (con't)	PDC2 (con't)	PDC3 (con't)	PDC4 (con't)	PDC5 (con't)	PDC6 (con't)
12:00pm - 1:15pm	EPS Luncheon @ Vigro1-4					
1:15pm - 2:25pm	Technology Innovation Showcase - Session 1 (70 min) | Quiz & Prizes Included					
Venue	Aquarius 1	Aquarius 2	Aquarius 3	Aquarius 4	Gemini 1	Gemini 2
2:25pm - 3:10pm	**Materials and Processing 1**	**TSV/Wafer Level Packaging 1**	**Mechanical Simulation & Characterization 1**	**Interconnection Technologies 1**	**Thermal Management and Characterization 1**	**Emerging Technologies**
	P372 (111)-oriented nanotwinned/nanograined bilayer Cu for post-Q-time low temperature Cu-Cu bonding	P168 Thermally Reliable Through Glass Via Filling with Ni-Fe Alloy for Advanced 3D Packaging	P172 Thin Fan-Out Package Characterization and Evaluation	P266 Surface Treatment for Wafer Bonding using Atmospheric Vapor Plasma Technology	P165 Novel TIM1 paste for Enhanced Thermal Management	P326 3D Surface Ion Trap Process Development for Quantum Applications
	P167 Enhancing Wafer Bonding Strength via Surface and Dielectric Modification Using Plasma Activation Process	P319 RDL-first FOWLP Development for III-V Semiconductor Chips in RF Applications	P255 Board level solder reliability and package stress for TSiCV UBM/bump IC package design	P185 Study of Extremely Low Temperature Organic Hybrid Bonding with Grain Engineered Cu	P142 PIV-Based Study of Heat Dissipation and Clogging phenomenon of TiO_2 Nanofluid in Microchannels	P161 2.5D Cryogenic Packaging for Advanced Quantum Processors
	P382 Water Vapor Permeation in Low-Temperature Processable Polyimide Materials for Reliable Polymer Hybrid Bonding	P302 Mitigating Connected PAD Corrosion in Hybrid Bonding	P156 Experimental and numerical analysis of a fan-out BGA Chip package reliabilities under drop test loads	P355 Bond line thickness stability of Cu sintering for automotive power module packaging		P208 Wafer-level Processes for the Manufacturing of Encapsulated Flexible Polymer-Based Implants
3:10pm - 4:40pm	Interactive Presentation (Poster), Exhibition and Coffee Break outside Exhibition Hall (Leo 1-4)					
Venue	Aquarius 1	Aquarius 2	Aquarius 3	Aquarius 4	Gemini 1	Gemini 2
4:40pm -5:40pm	**Materials and Processing 2**	**Advanced Packaging 1**	**Mechanical Simulation & Characterization 2**	**Interconnection Technologies 2**	**Thermal Management and Characterization 2**	**Assembly and Manufacturing Technology 1**
	P343 Chip Stacking: Impact of Chip Spacing in C2W hybrid bonding on Temporary Bonding and Debonding	P303 Using WGAN-Based Data Augmentation Machine Learning Algorithm for Estimating the Equivalent Material Properties	P241 Electric-Thermal Coupled Transient Simulation for a Schottky Diode with Temperature Dependent Resistivity of Epitaxial Layer	P188 A Novel Interface Characterization Technique for Hybrid Bonding Process Optimization	P251 DIMM Thermal Performance Enhancement with Heat Spreader and Advanced Cooling Solutions	P201 High-Density Interconnect RDL-FPC Hybrid Substrate for Compact SiP Packaging
	P246 Addressing CMP Process Challenges on Temporarily Bonded Wafers for Chip-to-Wafer Hybrid Bonding Applications	P354 Innovation and Efficiency in 3D Packaging Enabled by Optimized Integration Processes	P332 Prediction of Void-induced Crack Propagation within Underfill using the Meshless Material Point Method	P174 Gas-Free & Nano TiO2-Coated Ag Bonding Wire for Replacing Au Wire	P223 CFD and Surrogate Model-Driven Optimization of Two-Phase Immersion Cooling Configurations	P365 Novel UV-USP Laser Grooving and Plasma Dicing Separation Schemes for Next Generation Advanced Packaging
	P356 Analysis of SiO_2 surface chemistry by quasi-in situ XPS during N_2 plasma activation for SiO_2/SiO_2 bonding	P275 Seamless Heterointegration of Components: Advancements in Fanout Technology and Thermal Solutions in SIP	P271 Enhancing Predictive Accuracy of Warpage and Reliability for Advanced Packages by Modelling Accurate Poisson’s Ratio in Finite Element Analysis	P280 High-AR, Fine-Pitch Through-Mold Interconnect Fabrication for Heterogeneous Integration of HPC	P153 Thermal Design and Power Dissipation of Advanced Package with Heterogenous Integration	P173 Is Flash Lamp Annealing a Relevant Wafer Debonding Technique?
	P362 Applicability of Both-Sided Flash Lamp Annealing (FLA) Method on Heat Treatment Cu Plating Thin Film and Low Dielectric Resin Films	P102 A Packaging Structure for an Antenna-in-Package Module	P294 Optimization of Warpage and Mechanical Properties for Stacked SIP Package	P144 Interfacial Reactions of BiIn and SnBi Solders React with Cu Substrate		P301 Cost efficient Infrared Laser debonding technology enabled by Si carrier reuse
05:40pm - 06:45pm	EPTC Sponsors & Exhibitors Networking Cocktail Session – Co-Hosted with Lam Research (Diamond Sponsor)					

DAY 3: December 4, 2025 (AM)

Venue	Aquarius 1	Aquarius 2	Aquarius 3	Aquarius 4	Gemini 1	Gemini 2
8:45am -9:45am	**TSV/Wafer Level Packaging 2**	**Smart Manufacturing and Equipment Technology 1**	**Mechanical Simulation & Characterization 3**	**Quality, Reliability & Failure Analysis 1**	**Advanced Packaging 2**	**Assembly and Manufacturing Technology 2**
	P106 Adaptive Patterning®: Unlocking Scalable Density in Embedded Bridge Die Interposer	P242 Connectivity-Guided Feasibility Masking for Efficient Chiplet Placement in 2.5D Packaging via Reinforcement Learning	P177 Study on the Warpage Simulation and its Validation of Lidded FCBGA with Indium alloy TIM	P140 Studies and Elimination of F-induced Corrosion on Al Bondpads and Wafer Fabrication Process Improvement	P312 Characterization of PVD Seed Layer Contact Resistance in 2.0 to 20.0 µm Vias	P273 Selective Post-Soldering Volume Adjustment for Improved Co-Planarity of C4 Bump Interfaces
	P285 A Simplified 1-Tier TSV MIM Trench Capacitor Process Integration	P263 Real-Time 3D Reconstruction for Wire Bonding Using Multi-View Projection and EM Polynomial Modelling	P233 A Shock Vibration Calculation Method Considering Viscoplastic Behavior of Packaging Systems	P228 Annealing effect for Backside Metallization of SiC device	P150 112 Gbps SERDES Channel Design with 2.5D Sub-Micron BEOL Interconnect	P178 Aerosol Jet Printing of a Copper Nanoparticle Ink by Controlling the Wetness of Aerosols
	P218 Spectroscopic Critical Dimension (SCD) Metrology for Copper Dishing Control in Hybrid Bonding	P186 Defect Localization in Material Surfaces Using retinal CSRF kernel and Statistical Peak Profiling	P113 Delamination Effect Investigations Near RDL and UBM in WLCSP Packages	P306 Direct Bonding of Aluminum and Polypropylene in High-Reliability Structural Interfaces	P151 Advanced Bevel Deposition for Enhanced Yield and Cost Efficiency in Wafer-Level Bonding	P162 Heat Release Tape Characterization for Panel Level Packaging
	P111 Process-induced parasitic surface conduction (PSC) in SOI substrates for 3D-integrated RF front-end applications	P187 nhancing Wire Bonding Quality Prediction with a Physics-Informed Ensemble Learning Framework	P368 Feasibility Study of Stacked Sub-THz Band AiP Modules Based on Warpage and Stress Analysis	P219 Nanoindentation tests and constitutive study of sintered nano-silver	P307 Physics-Informed Graph Convolutional Neural Network for Scalable, and Accurate Thermal Analysis of 2.5D Chiplet-based Systems	P175 Reliability Evaluations of Pb-free Solder Joint Formed Using Sn-Ag-Cu solder ball and Sn-Bi-Ag solder paste
9:45am -10:30am	45min Coffee Break outside Exhibition Hall (Leo 1-4)					
10:30am -11:00am	**Invited Talk 1:** Dr. Dielacher Bernd (EVG) The Critical Role of Wafer Bonding in Next-Generation Interconnect Scaling	**Invited Talk 2:** Prof. Harald Kuhn (Fraunhofer ENAS) Innovation and Steps in Hetero-Integration	**Invited Talk 3:** Yasuhiro Morikawa (ULVAC Inc) Polymer Fine Pattern Formation based upon Plasma Etching Technology for High Density RDL Interposer	**Invited Talk 4:** Inohara Masahiro (KIOXIA) Accelerating the Evolution of NAND Flash Memory with Bonding Technologies	**Invited Talk 5:** Dr Mushuan Chan (SPIL) High Layer RDL Process Technology for Heterogenous Integration Package	**Invited Talk 6:** Dr Sajay BG (IME) Heterogeneously Integrated Wafer-Level Processed CPO Enginers for Next Gen AI/ML Data Centers
Venue	Vigro 1-4					
11:00am - 12:10pm	Technology Innovation Showcase Session 2 (70 min) | Quiz & Prizes Included					
Venue	Vigro 1-4					
12:10pm -1:15pm	EPTC Luncheon					

	DAY 3: December 4, 2025 (PM)					
12:00pm -1:15pm	EPTC Luncheon					
Venue	Aquarius 1	Aquarius 2	Aquarius 3	Aquarius 4	Gemini 1	Gemini 2
1:15pm -2:00pm	**Materials and Processing 3**	**Thermal Management and Characterization 3**	**Mechanical Simulation & Characterization 4**	**Interconnection Technologies 3**	**Advanced Packaging 3**	**Electrical Simulations & Characterization**
	P164 Metallurgical properties of Sn-3.0Ag-0.5Cu solder joints with Alumina layer deposition	P191 Magnetohydrodynamic Liquid Cooling Embedded in PCBs for High-power Electronics	P252 Evaluating Dummy Die Sizes and Compound Adjustments to reduce Wafer Warpage in FOEB-T Packaging.	P202 Comparative wear-out study and characterization methods for Pure and Alloyed Copper wires	P320 Ka-Band Ultra-Short Die-to-Antenna Interconnect Enabled by Embedded Glass Fan-Out Packaging	P289 Development of PDK Library for Accurate Modelling of 2.5D Interconnect Structures in Heterogeneous Integration
	P211 Wettability, Mechanical Properties and IMC of SiC nanoparticle-reinforced Sn-58Bi solders on Cu substrates under multiple reflow cycles	P247 Thermal Performance of MEMS Cross-flow Heat Exchangers Subjected to External Heat Transfer	P352 Statistical Evaluation of Bond Strength Variation in Hybrid Bonding Interfaces	P261 Microstructure Evaluation of Engineered Cu for Low-Temperature Cu-Cu Hybrid Bonding	P227 development of a Wideband Energy Harvesting Circuit Utilizing Terrestrial Digital Broadcast Signals	P169 Characteristics in the quasi-millimeter wave band of planar transmission lines formed on flexible substrates
	P304 Impact of Solder Powder Size on Cleaning Efficiency in Chip Resistor Assemblies for Future Advanced Packaging	P270 Numerical Investigation of Embedded Micro-Pin Fin Two-Phase Liquid Cooling for Dual-Chip Stacks in HPC & AI Applications	P220 Nanoindentation Test and Crystal Plasticity Finite Element Model of SAC305 Solder Joint Considering Crystal Orientation	P317 Toward lifetime prediction under variable load conditions in power electronics	P146 Optimization of Shielded Capacitive Power Transfer (S-CPT) Systems Using Slotted Electrodes	
2:00pm - 3:30pm	Interactive Presentation (Poster), Exhibition and Coffee Break outside Exhibition Hall (Leo 1-4)					
Venue	Aquarius 1	Aquarius 2	Aquarius 3	Aquarius 4	Gemini 1	Gemini 2
3:30pm -4:15pm	**Interconnection Technologies 4**	**Mechanical Simulation & Characterization 5**	**Advanced Packaging 4**	**Assembly and Manufacturing Technology 3**	**Thermal Management and Characterization 4**	**Materials and Processing 4**
	P299 Fluxless Die to Die Bonding of 10µm Ultra-fine Pitch Microbump	P369 Characterization and Modelling of Inelastic Behavior of Epoxy Molding Compounds	P367 Low Temperature Post Bond Anneal for Hybrid Bonding enabled by Interfacial (IF) Metal Capping – An Assessment of Reliability	P196 Growth Behaviour of Intermetallic Compounds in Cu-Sn3.5Ag Solder Joints with Different furnace cooling rate	P371 Direct-Bonded Manifold-Jet-Impingement Cooling for High-Performance AI Chips	P379 Enhancing Yield Performance in Chip-to-Wafer Hybrid Bonding in Advanced Packaging
	P314 Novel Ultrasonic Flip Chip Bonding Approach utilizing electroplated Aluminium pillars for Advanced Packaging	P349 Real-time Effective Mechanical Property Characterization of Redistribution Layer (RDL) for Chiplet Integration	P374 WireBond Challenges of Copper Clip for Multi-Die Controller MOSFET Package	P158 Hybrid Evaluation of Pure Argon Plasma Treatment for Enhanced Wire Bonding and Manufacturing Efficiency in Microelectronics	P334 High-Temperature Pressure Mapping of TIM Interfaces for Improved Thermal Simulation Accuracy	P234 Study on Backside Metallization for the S-SWIFT(TM) Package
	P157 Investigation of Cu bonding wire lifetime under accelerated temperature environments	P305 StressScore for benchmarking AI generated stress image of advanced packaging	P265 Characterization on Fan-Out Heterogeneous Integration Packaging for Premium Smartphone	P131 Impact Of Modified Layers Due to Stealth Dicing Process on The Die Strength	P222 Operando Thermal Analysis of CPU and PCB using a Pixel-level Emissivity Correction Method	P189 Study of Coverage Decay Mechanism of Liquid Metal Filler TIM for Advanced Package Application
Venue	Vigro 1-4					
4:15pm - 5:25pm	Technology Innovation Showcase Session 3 (70 min) | Quiz & Prizes Included					
5:25pm - 6:10pm	**Interconnection Technologies 5**	**TSV/Wafer Level Packaging 3**	**Materials and Processing 5**	**Assembly and Manufacturing Technology 4**	**Quality, Reliability & Failure Analysis 3**	**Thermal Management and Characterization 5**
	P298 Morphology-Controlled Sintering of High-Performance Copper Interconnects for Cost Effective Power Electronics	P105 Analysis of Cu and dielectric layer interfacial delamination in chip redistribution layer	P116 Study on Microstructural Evolution Mechanisms of Amorphous SiO2 in Through Glass Via Wafer during Thinning	P315 Automated In-Line Metrology of Advanced Package Interconnections using a High-Speed 3D X-ray System	P115 Defect Z-depth Determination in 2.5D IC Using Magnetic Field Imaging	P163 Thermal Performance Enhancement of Stacked Packages using Silicon-Based Heat Spreading Die
	P179 A Molecular Dynamics Study of Grain Size Effects on Cu-Cu Interfacial Void Reduction in Direct Bonding Interconnect	P126 Mitigation of Cu Nodule Formation in High Open Area Products for Electroplated Cu RDL Applications	P272 Optimizing SSD Performance with One-Part Thermal Gap Fillers: A Sustainable Approach	P224 Mass Transfer solution for Micro-LEDs based displays	P200 In-Situ Package Level Relative Humidity Measurement using Wet-Bulb and Dry-Bulb Temperatures	P381 Solid-State On-Chip Thermal Management Using Micro-Thermoelectric Devices
	P243 In-situ AFM Analysis of Thermal Expansion of Cu Pads with Varied Grain Characteristics	P256 Surface Activation and Bonding Mechanisms of SiCN and TEOS Dielectrics for Low-Temperature Hybrid Bonding	P316 Cost-Effective Wafer Level Micro Bumping Solution for Advanced Packaging		P358 AI-empowered 3D X-ray analysis of solder joint cracking after board level vibration testing	P322 Thermal Sensitivity Analysis of SoIC Face-to-Back Stacking Using Foundation Models for Physics
06:15pm - 08:30pm	EPTC Banquet Dinner					

DAY 4: December 5, 2025 (AM)

Venue	Vigro 1-4					Gemini 2
8:45am – 10:00am	Technology Innovation Showcase Session 4 (75 min) | Quiz & Prizes Included					R10 EPS Chapter Officers’s Meeting
10:00am - 11:00am	60min Coffee Break outside Exhibition Hall (Leo 1-4)					
Venue	Aquarius 1	Aquarius 2	Aquarius 3	Aquarius 4	Gemini 1	Gemini 2
11:00am -11:30am	**Invited Talk 7:** Dr Kathy Yen (TSMC) From Cloub AI to Edge AI: Driving Innovation with Advanced Packaging	**Invited Talk 8:** Dr Takenori Fujiwara (Toray Industries) Polymer Bonding Technology for Semiconductor Advanced Packaging	**Invited Talk 9:** David Gani (STMicro) Challenges and Advantages in Panel Level Packaging	**Invited Talk 10:** Dr Tan Yik Yee (YOLE) AI is Accelerating the Advanced Packaging	**Invited Talk 11:** Jonathan Abdilla (BESI) Hybrid Bonding and Fluxless TCB: Defining the Sub 10um Interconnect Roadmap for 3D HI	**Invited Talk 12:** Dr Zhao Yi (Zhuhai Silicon Chip Technology) Advanced Packaging EDA's New Paradigm: Collaborative Innovation Revolution for Design-Simulation-Verification in the 2.5D/3D Era
	Advanced Packaging 6	**Smart Manufacturing and Equipment Technology 3**	**Mechanical Simulation & Characterization 6**	**Interconnection Technologies 6**	**Quality, Reliability & Failure Analysis 4**	**Materials and Processing 6**
11:30am -11::45pm	P350 n77/n79 Antenna-plexer with BAW and Glass-IPD Technology for 5G Applications	P193 AI-driven Pixel-Level Defect Localization using Magnetic Current Images	P321 Degradation Mechanism of Frequency Stability in MEMS Resonant Accelerometers	P143 UV-Assisted Fluxless Thermal-Compression Bonding Under Ambient Conditions	P132 Anomalyspy: A Generative Defect Localization in Semiconductor Packages, with X-ray Microscopy	P240 Copper Pillar Bump FCBGA Underfill Process Characterization for Automotive Application
11:45am -12::00pm	P308 Power and Performance Comparison between FPGA-Optics Integrated 3D SiP and equivalent board level test hardware	P236 Research on Intelligent Prediction of 3D-IC Packaging Injection Molding Based on Machine Learning	P370 Dev of a Reproducible, Stable, and Scalable Eval Routine for Lifetime Assessment of Power and Microelectronic Devices	P244 Characterization of Fine Line Width/Spacing RF Interconnects for Co-Packaged Optics with High I/O Density	P180 Cu/SiCN wafer-to-wafer hybrid bonding interface reliability down to 400 nm pitch	P212 Enhanced Reliability of Large BGA Assemblies for AI Server and HPC Application
12:00pm- 12:15pm	P361 Process Developments of Chip-to-Wafer assembly with HPC and Photonics Chiplets on large RDL-first interposer	P359 Cross-Domain Adaptation of Automated 3D X-ray Defect Detection from HBM to Optical Transceivers	P329 Advancing Electronic Package Reliability Analysis by Predicting Solder Joint Strain Patterns Using Neural Networks	P138 Design of Wire Bonding Schemes for Reliability of CQFP Packages under Vibration Test	P375 Investigations on the Mutual Effects of Electromigration and Thermal Fatigue failures of TSV Interconnects	P281 Development of an Epoxy Lid Adhesive to Improve Thermal Reliability in Semiconductor Packages
Venue	Vigro 1-4					
12:15pm -1:30pm	Conference Lunch					

DAY 4: December 5, 2025 (PM)

12:15pm -1:30pm	Conference Lunch					
Venue	Aquarius 1	Aquarius 2	Aquarius 3	Aquarius 4	Gemini 1	Gemini 2
	Advanced Packaging 7	**Materials and Processing 7**	**TBC**	**Smart Manufacturing and Equipment Technology 3**	**Advanced Optoelectronics and Displays**	**Mechanical Simulation & Characterization 7**
1:30pm - 1:45pm	P260 Demonstration of Integrated Passive Devices in Glass substrate using TGV process	P129 Pressure Sintering Mechanism of Ag Nanoparticles Based on The Master Sintering Curve and Visualization of Sinterability	P323 Backside Metal Interconnect for High Performance RF Interposer	P348 nferring Wire Length and Depth from Magnetic Field Images via Deep-Spatial Physics Informed Model	P267 Assembly of optical micro-ring resonator-based ultrasound sensor for photoacoustic imaging	P139 Key Insights into Design for Reliability of 3D NAND Packages in Solid-State Drive
1:45pm - 2:00pm	P154 Residue Free TaN Etch Method for MIM Capacitor in Advanced Packaging	P221 High-Performance Graphene Coatings for Superior Thermal and Mechanical Properties in Electronic Packaging Enclosures		P213 Device-to-Package Electrothermal Performance Prediction of Power MOSFETs via Coupled Iterative Dual-Artificial Neural Networks	P104 High Coupling Efficiency Adhesive for Photonic Packaging	P373 A novel wafer warpage numerical model considering further shrinkage of epoxy molding compound
2:00pm - 2:15pm	**Invited Talk 13** Fu Chao (WinTechNano) Labless Enable Effective FA of Electronics Packages through Scientific Approach	**Invited Talk 14** Hidenori Abe (Resonac) Advanced Packaging Materials Innovation through Co-Creative Activities and Trends in Advanced Packaging Processes	**Invited Talk 15:** Dr Min Woo Rhee (Samsung) Understanding of Hybrid Bonding Mechanism by Utilizing Molecular Dynamics Approach	P209 Thermal- and Wirelength-Aware Chiplet Placement in 2.5D Systems Through Multi-Agent Reinforcement Learning	P253 2.5D PIC Photonic Interposer Engine for Next Generation Photonic Link CPO of High-Performance Computing and Data Communications	P127 Development of Warpage Predictive Models using Physics-Driven Simulation
2:15pm - 2:30pm				P264 Generative AI-Powered Defect Detection for 3D X-ray Microscopy Scans of High Bandwith Memory Bumps	P206 An Integrated Computational Materials Engineering approach for Anisotropic Conductive Films	P239 Thermal and mechanical properties optimization of TGV interposer for 2.5D integrated transceiver
2:30pm – 3:00pm	30min Coffee Break outside Exhibition Hall (Leo 1-4)					
Venue	Aquarius 1, 2 and 3 (combined rooms)			Aquarius 4	Gemini 1	Gemini 2
3:00pm - 3:30pm	**Heterogeneous Integration Roadmap (HIR) workshop** Theme: Interconnects - Design and Manufacturing of Complex HI Structures Opening: Kitty Pearsall Design for Manufacturability of > 1 kW: Gamal Refai Ahmed (AMD) Design – Photonics: Amr S Helmy (University of Toronto) Manufacturability – HBI: Loke Yuan Wong (Applied Materials) Manufacturability – Nelson Fan (ASMPT) Manufacturability – CPO (IME, A*STAR) Round Table Discussion “Why HBI/CPO HVM Adaption is in Slower Pace Despite all the Buzz?” Moderator: Wong Shaw Fong (Intel)			**Advanced Packaging 8**	**Quality, Reliability & Failure Analysis 2**	**Materials and Processing 8**
				P170 Development of Embedded Bridge Die interposer Using Fan-Out Packaging for Heterogeneous Integration of NPUs and HBMs	P141 Short-Circuit Behavior and Failure Mechanism Analysis of Double-Trench SiC MOSFETs	P363 Comparative Evaluation of FCVA and High-Current Arc Deposited ta-C Films for Hermetic Encapsulation
				P287 HI of High-Performance Compute, Memory and Photonic Engine Chiplets on Large Molded Interposer package	P276 A Modified Test Vehicle Incorporating DNP-Induced Strain Gradients for Single-Specimen Fatigue Life Assessment of Solder Joints	P118 Enhancing Electrochemical Migration Resistance of Sintered Silver by Ceria Additives for Die Attachment Applications
3:30pm - 3:45pm				P378 MDQFN™: Panel-Level QFN for Scalable, Cost-Effective Semiconductor Packaging	P147 Correlation Between Thermal Cycling Ramp Rates and its Respective Solder Joint Reliability	P117 Study on Solder Core Ball Using Sn-Bi Plating for Low-Temperature Bonding
3:45pm - 4:00pm				P199 Ultra-low-TTV Glass Carrier and Temporary Bonding Method to Enable Wafer Ultra-thinning	TBC	P384 Development and Monitoring of Gold Electroplating Process on 300mm Wafer Level
4:00pm - 4:15pm						
4:15pm - 4:30pm						
4:30pm – 5:00pm						
5:10pm - 5:30pm	Closing Ceremony and Lucky Draw @ Aquarius 1, 2 and 3 (combined rooms)					